



Case No.: AMKOR-003A
Patent Appln.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Jeffrey Alan Miks)	Group No.:	2826
Serial No.:	10/054,124)	Examiner:	Williams, Alexander
Filed:	01/22/2002)		
For:	SEMICONDUCTOR PACKAGE INCLUDING LEADS WITH VERTICALLY DOWNSET INNER ENDS)		

DECLARATION OF JEFFREY ALAN MIKS UNDER 37 C.F.R. § 1.131

I, Jeffrey Alan Miks, hereby declare as follows:

1. I am employed with Amkor Technology, Inc., and currently hold the title of Director-Product Memory Cards. I have personal knowledge of the following facts and can competently testify thereto.
2. I am the sole inventor of the invention described and claimed in U.S. Patent Application Serial No. 10/054,124 ("the '124 Application") entitled "Semiconductor Package Including Leads with Vertically Downset Inner Ends." Attached hereto as Exhibit A is a true copy of a Declaration for Utility or Design Patent Application ("Patent Declaration") executed by me on January 21, 2002, as evidenced by my dated signature which appears on the second page thereof. The Patent Declaration specifies that I am the original, first, and sole inventor of the subject matter which is claimed and for which a patent is sought in the '124 Application.
3. Attached hereto as Exhibit B is a true copy of page 5 of Engineering Notebook #105 ("notebook entry"). The notebook entry bears my signature dated March 2, 2001 and was witnessed

by Thun Kham on the same date. The notebook entry sets forth a sketch of the invention of the '124 Application and indicates its primary concepts, namely: a raised ring concept implemented using a raised inner lead tip and a raised ground ring. Accordingly, the notebook entry demonstrates that the invention of the '124 Application was conceived by me at least as early as March 2, 2001. The notebook entry was originally attached as Appendix B to the Amkor Technology Disclosure Form bearing Patent Tracking #2K1039 described below.

4. Attached hereto as Exhibit C is a true copy of an Amkor Technology Disclosure Form bearing Patent Tracking #2K1039 ("Disclosure Form"). The Disclosure Form evidences that the invention of the '124 Application was conceived by me at least as early as March 2, 2001 (page 3) and discloses primary components of the invention, namely: (1) raised die paddle wire bond ring; and (2) raised inner lead tips for wire bond (page 3). The Disclosure Form bears my signature dated March 9, 2001 and was witnessed by three additional persons on March 13, 2001.

5. I made a presentation of the invention described and claimed in the '124 Application to an in-house invention review counsel on June 13, 2001. As a result of this presentation, authorization was given for the preparation of the '124 Application.

6. I participated in the preparation of the '124 Application with outside patent counsel in the time frame of August 2001 through the filing of the '124 Application, and reviewed the '124 Application before executing the Patent Declaration on January 21, 2002, attached hereto as Exhibit A.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that

such willful false statements may jeopardize the validity of the '124 Application or any patent issued thereon.

Date: 2/14/03

By:


Jeffrey Alan Miks

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